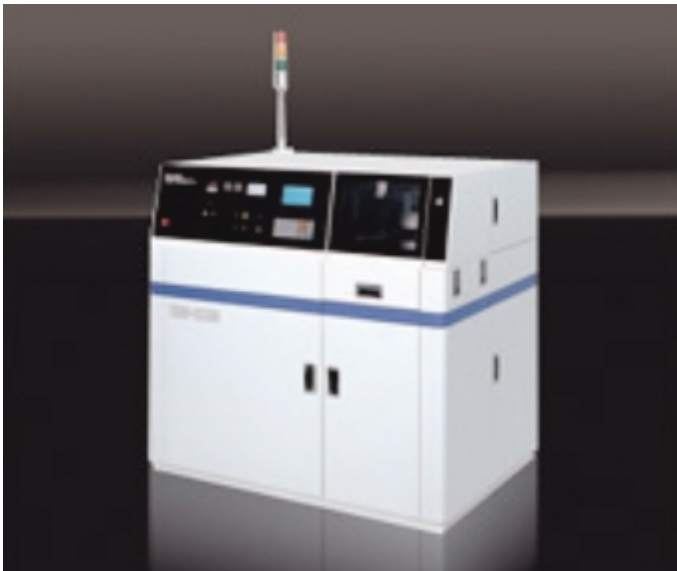


200mm Fully-Automatic UV Irradiation System

RAD-2000F/8



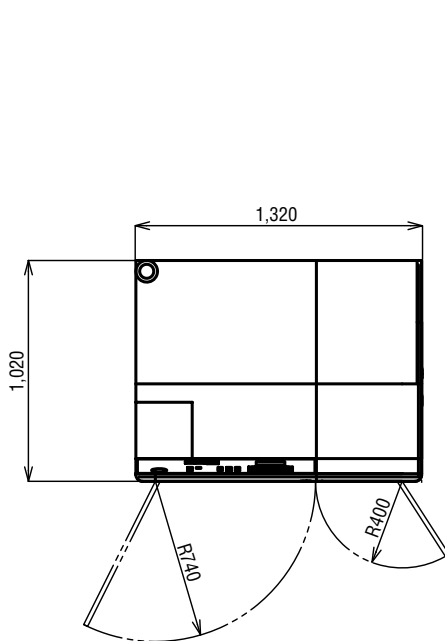
Outline

- Fully-automatic UV irradiation system used for curing UV type dicing tape.
- Applicable for ring frame sizes used for 150mm and 200mm wafers.

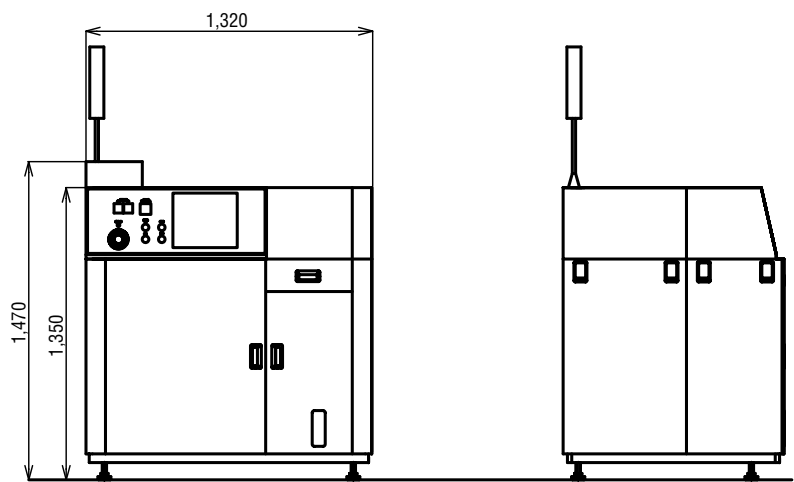
Option ·Host Communication Function (Communication Format :
Conforms to SECS-I and HSMS/Software : Conforms to GEM)

Suitable Tapes ·Dicing tape : Adwill D series
·Dicing die bonding tape : Adwill LE Tape

External View



Top View



Front View

Left Side View

Unit:mm

Facility

| | | |
|------------------------|----------------------|-----------------------------------|
| Power Supply | Voltage | : AC200-230V ±10% (AC190-253V) |
| | Frequency | : 50/60Hz |
| | Phase | : single phase |
| Air Supply | Power consumption | : 5.0kW |
| | Air pressure | : 0.5-0.8MPa |
| | Air consumption | : >250L/min (ANR) |
| Nitrogen Source | Nitrogen pressure | : 0.29MPa |
| | Nitrogen consumption | : 30-50L/min (ANR) |

Applicable Wafer Size 150mm, 200mm

Size Width : 1,320mm
Depth : 1,020mm
Height : 1,470mm
(excluding the signal tower)

Weight 900kg

UPH 100wafers/hour

The above processing capacity is based on following conditions:

Wafer : 200mm diameter non-polished mirror wafer
Ring frame : for 200mm wafer